

Heat sink for plastic ball grid array on IC chip surface has antioxidant coating on protruding body mounted on chip surface to form an elastic connecting structure using material adhesion

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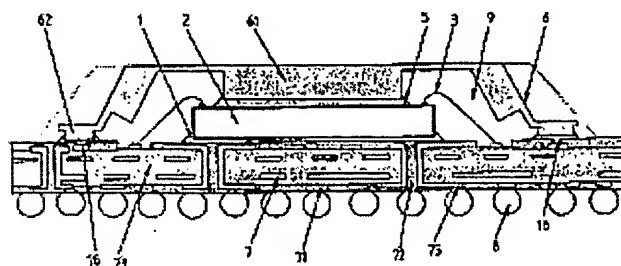
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Abstract of FR2803098

The heat sink has a protruding body on its inside, a coating of antioxidant deposited on the protruding body, a substrate with an earth connection point connected to a heat sink connection finger, a silver adhesive connecting the chip to the substrate and heated to mount the chip on the substrate and an elastic, heat-conducting adhesive deposited onto the surface of the protruding body or chip. The protruding body is connected to the chip surface using a joining arrangement and is mounted on the chip surface to form an elastic connecting body structure using a material adhesive process.



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